



## Neoconix Releases Low-Profile LGA1366 Socket

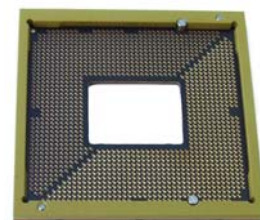
SUNNYVALE, CA September 28, 2009 – Neoconix has teamed up with Intel to develop a low-profile socket alternative for Intel’s Jasper Forest family of processors based on the Nehalem-EP architecture. Intel designed the new processor family to provide added performance with the embedded market in mind, where space and power are at a premium. Neoconix’ new low-profile socket allows Intel’s customers to maximize the performance and power advantages of this new architecture.

The new low-profile socket from Neoconix supports Intel’s LGA1366 footprint and offers a 50% reduction in mated height compared to traditional LGA1366 sockets. For companies deploying systems with the AMC, VME, and ATCA standards, the lower socket profile translates into added clearance for heat dissipation – up to an additional 20% in power dissipation capability in some cases. The socket passes MIL-STD-810F tests for increased reliability in rugged environments. Additionally, the socket offers a reduction in mass and requires a smaller keep-out area than the traditional sockets.

Neoconix’ new low-profile socket will enable Intel’s embedded customers to deploy the world’s most advanced processors into smaller and more thermally sensitive environments than was ever possible before. “Neoconix’ low profile interconnect products are quickly becoming an essential part of today’s smaller, more power-efficient, rugged embedded systems” said Larry Dittmann, Executive Vice President of Business Development at Neoconix.

Neoconix’ sockets and interposers use proprietary PCBeam™ technology, featuring all-metal spring beams that are permanently embedded onto a dielectric substrate in a high-density configuration. Photolithography and etch are used to define the contact elements, and this enables a combination of design flexibility, true-position accuracy, and electro-mechanical performance that has not historically been possible.

The socket is available for standard eutectic reflow process. Lead-free versions can be made available upon request.



**Neoconix Low-Profile  
LGA1366 Socket**

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**Neoconix, Inc.** is a premier supplier of high density, high performance electrical connectors and interconnects. The company leverages its advanced printed circuit board (PCB) processing techniques to enable high-performance connectors at low cost. Characterized by exceptional dimensional control at fine feature sizes, Neoconix’s PCBeam™ technology is ideal for a broad set of Board-to-Board, Flex-to-Board and IC Device-to-Board applications. Neoconix’s products and technologies are used in many electronics markets, including computing, military, mobile electronics, telecommunications, and test equipment.